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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj32ga102t-i-ss

TABLE 1-2: PIC24FJ64GA104 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	28-Pin SPDIP/ SOIC/SSOP	28-Pin QFN	44-Pin QFN/ TQFP			
RP0	4	1	21	I/O	ST	Remappable Peripheral (input or output).
RP1	5	2	22	I/O	ST	
RP2	6	3	23	I/O	ST	
RP3	7	4	24	I/O	ST	
RP4	11	8	33	I/O	ST	
RP5	14	11	41	I/O	ST	
RP6	15	12	42	I/O	ST	
RP7	16	13	43	I/O	ST	
RP8	17	14	44	I/O	ST	
RP9	18	15	1	I/O	ST	
RP10	21	18	8	I/O	ST	
RP11	22	19	9	I/O	ST	
RP12	23	20	10	I/O	ST	
RP13	24	21	11	I/O	ST	
RP14	25	22	14	I/O	ST	
RP15	26	23	15	I/O	ST	
RP16	—	—	25	I/O	ST	
RP17	—	—	26	I/O	ST	
RP18	—	—	27	I/O	ST	
RP19	—	—	36	I/O	ST	
RP20	—	—	37	I/O	ST	
RP21	—	—	38	I/O	ST	
RP22	—	—	2	I/O	ST	
RP23	—	—	3	I/O	ST	
RP24	—	—	4	I/O	ST	
RP25	—	—	5	I/O	ST	
RTCC	25	22	14	O	—	Real-Time Clock Alarm/Seconds Pulse Output.
SCL1	17	14	44	I/O	I^2C	I2C1 Synchronous Serial Clock Input/Output.
SCL2	7	4	24	I/O	I^2C	I2C2 Synchronous Serial Clock Input/Output.
SDA1	18	15	1	I/O	I^2C	I2C1 Data Input/Output.
SDA2	6	3	23	I/O	I^2C	I2C2 Data Input/Output.
SOSCI	11	8	33	I	ANA	Secondary Oscillator/Timer1 Clock Input.
SOSCO	12	9	34	O	ANA	Secondary Oscillator/Timer1 Clock Output.
T1CK	12	9	34	I	ST	Timer1 Clock Input.
TCK	17	14	13	I	ST	JTAG Test Clock Input.
TDI	21	18	35	I	ST	JTAG Test Data Input.
TDO	18	15	32	O	—	JTAG Test Data Output.
TMS	22	19	12	I	ST	JTAG Test Mode Select Input.

Legend: TTL = TTL input buffer
ANA = Analog level input/output
ST = Schmitt Trigger input buffer
I^2C™ = I^2C/SMBus input buffer

2.4 Voltage Regulator Pins (ENVREG/DISVREG and VCAP/VDDCORE)

Note: This section applies only to PIC24FJ devices with an on-chip voltage regulator.

The on-chip voltage regulator enable/disable pin (ENVREG or DISVREG, depending on the device family) must always be connected directly to either a supply voltage or to ground. The particular connection is determined by whether or not the regulator is to be used:

- For ENVREG, tie to VDD to enable the regulator, or to ground to disable the regulator
- For DISVREG, tie to ground to enable the regulator or to VDD to disable the regulator

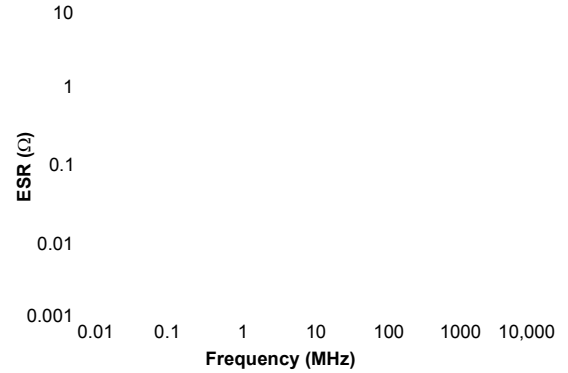
Refer to **Section 25.2 "On-Chip Voltage Regulator"** for details on connecting and using the on-chip regulator.

When the regulator is enabled, a low-ESR (<5Ω) capacitor is required on the VCAP/VDDCORE pin to stabilize the voltage regulator output voltage. The VCAP/VDDCORE pin must not be connected to VDD, and must use a capacitor of 10 μF connected to ground. The type can be ceramic or tantalum. A suitable example is the Murata GRM21BF50J106ZE01 (10 μF, 6.3V) or equivalent. Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

The placement of this capacitor should be close to VCAP/VDDCORE. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 28.0 "Electrical Characteristics"** for additional information.

When the regulator is disabled, the VCAP/VDDCORE pin must be tied to a voltage supply at the VDDCORE level. Refer to **Section 28.0 "Electrical Characteristics"** for information on VDD and VDDCORE.

FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP



Note: Data for Murata GRM21BF50J106ZE01 shown. Measurements at 25°C, 0V DC bias.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming (ICSP) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input low (VIL) requirements.

For device emulation, ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 26.0 "Development Support"**.

3.2 CPU Control Registers

REGISTER 3-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0(1)	R/W-0(1)	R/W-0(1)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DC:** ALU Half Carry/Borrow bit
1 = A carry out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry out from the 4th or 8th low-order bit of the result has occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(1,2)
111 = CPU interrupt priority level is 7 (15); user interrupts disabled
110 = CPU interrupt priority level is 6 (14)
101 = CPU interrupt priority level is 5 (13)
100 = CPU interrupt priority level is 4 (12)
011 = CPU interrupt priority level is 3 (11)
010 = CPU interrupt priority level is 2 (10)
001 = CPU interrupt priority level is 1 (9)
000 = CPU interrupt priority level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** ALU Overflow bit
1 = Overflow occurred for signed (2's complement) arithmetic in this arithmetic operation
0 = No overflow has occurred

bit 1 **Z:** ALU Zero bit
1 = An operation which effects the Z bit has set it at some time in the past
0 = The most recent operation which effects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry out from the Most Significant bit of the result occurred
0 = No carry out from the Most Significant bit of the result occurred

Note 1: The IPL Status bits are read-only when NSTDIS (INTCON1<15>) = 1.
2: The IPL Status bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1.

REGISTER 7-21: IPC6: INTERRUPT PRIORITY CONTROL REGISTER 6

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T4IP2	T4IP1	T4IP0	—	OC4IP2	OC4IP1	OC4IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	OC3IP2	OC3IP1	OC3IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T4IP<2:0>:** Timer4 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OC4IP<2:0>:** Output Compare Channel 4 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **OC3IP<2:0>:** Output Compare Channel 3 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 7-23: IPC8: INTERRUPT PRIORITY CONTROL REGISTER 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI2IP2	SPI2IP1	SPI2IP0	—	SPF2IP2	SPF2IP1	SPF2IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **SPI2IP<2:0>:** SPI2 Event Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **SPF2IP<2:0>:** SPI2 Fault Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

8.3 Control Registers

The operation of the oscillator is controlled by three Special Function Registers:

- OSCCON
- CLKDIV
- OSCTUN

The OSCCON register (Register 8-1) is the main control register for the oscillator. It controls clock source switching and allows the monitoring of clock sources.

The CLKDIV register (Register 8-2) controls the features associated with Doze mode, as well as the postscaler for the FRC Oscillator.

The OSCTUN register (Register 8-3) allows the user to fine tune the FRC Oscillator over a range of approximately ±12%. Each bit increment or decrement changes the factory calibrated frequency of the FRC Oscillator by a fixed amount.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R-0	R-0	R-0	U-0	R/W-x(1)	R/W-x(1)	R/W-x(1)
—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0
bit 15							bit 8

R/SO-0	R/W-0	R-0(3)	U-0	R/CO-0	R/W-0	R/W-0	R/W-0
CLKLOCK	IOLOCK(2)	LOCK	—	CF	POSCEN	SOSCEN	OSWEN
bit 7							bit 0

Legend:	CO = Clearable Only bit	SO = Settable Only bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits
- 111 = Fast RC Oscillator with Postscaler (FRCDIV)
- 110 = Reserved
- 101 = Low-Power RC Oscillator (LPRC)
- 100 = Secondary Oscillator (SOSC)
- 011 = Primary Oscillator with PLL module (XTPLL, HSPLL, ECPLL)
- 010 = Primary Oscillator (XT, HS, EC)
- 001 = Fast RC Oscillator with Postscaler and PLL module (FRCPLL)
- 000 = Fast RC Oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(1)
- 111 = Fast RC Oscillator with Postscaler (FRCDIV)
- 110 = Reserved
- 101 = Low-Power RC Oscillator (LPRC)
- 100 = Secondary Oscillator (SOSC)
- 011 = Primary Oscillator with PLL module (XTPLL, HSPLL, ECPLL)
- 010 = Primary Oscillator (XT, HS, EC)
- 001 = Fast RC Oscillator with Postscaler and PLL module (FRCPLL)
- 000 = Fast RC Oscillator (FRC)

Note 1: Reset values for these bits are determined by the FNOSC Configuration bits.

2: The state of the IOLOCK bit can only be changed once an unlocking sequence has been executed. In addition, if the IOL1WAY Configuration bit is '1', once the IOLOCK bit is set, it cannot be cleared.

3: Also resets to '0' during any valid clock switch or whenever a non-PLL clock mode is selected.

REGISTER 8-4: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ROEN:** Reference Oscillator Output Enable bit
1 = Reference oscillator is enabled on REFO pin
0 = Reference oscillator is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **ROSSLP:** Reference Oscillator Output Stop in Sleep bit
1 = Reference oscillator continues to run in Sleep
0 = Reference oscillator is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Primary Oscillator is used as the base clock. Note that the crystal oscillator must be enabled using the FOSC<2:0> bits; the crystal maintains the operation in Sleep mode.
0 = System clock is used as the base clock; base clock reflects any clock switching of the device

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divisor Select bits
1111 = Base clock value divided by 32,768
1110 = Base clock value divided by 16,384
1101 = Base clock value divided by 8,192
1100 = Base clock value divided by 4,096
1011 = Base clock value divided by 2,048
1010 = Base clock value divided by 1,024
1001 = Base clock value divided by 512
1000 = Base clock value divided by 256
0111 = Base clock value divided by 128
0110 = Base clock value divided by 64
0101 = Base clock value divided by 32
0100 = Base clock value divided by 16
0011 = Base clock value divided by 8
0010 = Base clock value divided by 4
0001 = Base clock value divided by 2
0000 = Base clock value

bit 7-0 **Unimplemented:** Read as ‘0’

Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance and pins configured as outputs continue to drive their previous value. After waking up, the TRIS and LAT registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/O will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>) the I/O pins are “released”. This causes the I/O pins to take the states configured by their respective TRIS and LAT bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

If a $\overline{\text{MCLR}}$ Reset event occurs during Deep Sleep, the DSGPRx, DSCON and DSWAKE registers will remain valid and the RELEASE bit will remain set. The state of the SOSC will also be retained. The I/O pins, however, will be reset to their $\overline{\text{MCLR}}$ Reset state. Since RELEASE is still set, changes to the SOSCEN bit (OSCCON<1>) cannot take effect until the RELEASE bit is cleared.

In all other Deep Sleep wake-up cases, application firmware must clear the RELEASE bit in order to reconfigure the I/O pins.

9.2.4.7 Deep Sleep WDT

To enable the DSWDT in Deep Sleep mode, program the Configuration bit, DSWDTEN (CW4<7>). The device Watchdog Timer (WDT) need not be enabled for the DSWDT to function. Entry into Deep Sleep mode automatically resets the DSWDT.

The DSWDT clock source is selected by the DSWDTOSC Configuration bit (CW4<4>). The postscaler options are programmed by the DSWDTPS<3:0> Configuration bits (CW4<3:0>). The minimum time-out period that can be achieved is 2.1 ms and the maximum is 25.7 days. For more details on the CW4 Configuration register and DSWDT configuration options, refer to **Section 25.0 “Special Features”**.

9.2.4.8 Switching Clocks in Deep Sleep Mode

Both the RTCC and the DSWDT may run from either SOSC or the LPRC clock source. This allows both the RTCC and DSWDT to run without requiring both the LPRC and SOSC to be enabled together, reducing power consumption.

Running the RTCC from LPRC will result in a loss of accuracy in the RTCC of approximately 5 to 10%. If an accurate RTCC is required, it must be run from the SOSC clock source. The RTCC clock source is selected with the RTCOSC Configuration bit (CW4<5>).

Under certain circumstances, it is possible for the DSWDT clock source to be off when entering Deep Sleep mode. In this case, the clock source is turned on automatically (if DSWDT is enabled), without the need for software intervention. However, this can cause a delay in the start of the DSWDT counters. In order to avoid this delay when using SOSC as a clock source, the application can activate SOSC prior to entering Deep Sleep mode.

9.2.4.9 Checking and Clearing the Status of Deep Sleep

Upon entry into Deep Sleep mode, the status bit, DPSLP (RCON<10>), becomes set and must be cleared by software.

On power-up, the software should read this status bit to determine if the Reset was due to an exit from Deep Sleep mode and clear the bit if it is set. Of the four possible combinations of DPSLP and POR bit states, three cases can be considered:

- Both the DPSLP and POR bits are cleared. In this case, the Reset was due to some event other than a Deep Sleep mode exit.
- The DPSLP bit is clear, but the POR bit is set. This is a normal Power-on Reset.
- Both the DPSLP and POR bits are set. This means that Deep Sleep mode was entered, the device was powered down and Deep Sleep mode was exited.

10.3 Input Change Notification

The input change notification function of the I/O ports allows the PIC24FJ64GA104 family of devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature is capable of detecting input Change-of-States even in Sleep mode, when the clocks are disabled. Depending on the device pin count, there are up to 31 external inputs that may be selected (enabled) for generating an interrupt request on a Change-of-State.

Registers, CNEN1 and CNEN2, contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin has a weak pull-up connected to it. The pull-up acts as a current source that is connected to the pin. This eliminates the need for external resistors when push button or keypad devices are connected. The pull-ups are separately enabled using the CNPU1 and CNPU2 registers (for pull-ups). Each CN pin has individual control bits for its pull-up. Setting a control bit enables the weak pull-up for the corresponding pin.

When the internal pull-up is selected, the pin pulls up to V_{DD} – 0.7V (typical). Make sure that there is no external pull-up source when the internal pull-ups are enabled, as the voltage difference can cause a current path.

Note:	Pull-ups on change notification pins should always be disabled whenever the port pin is configured as a digital output.

10.4 Peripheral Pin Select (PPS)

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. In an application that needs to use more than one peripheral multiplexed on a single pin, inconvenient work arounds in application code or a complete redesign may be the only option.

The Peripheral Pin Select feature provides an alternative to these choices by enabling the user's peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the microcontroller to their entire application, rather than trimming the application to fit the device.

The Peripheral Pin Select feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of any one of many digital peripherals to any one of these I/O pins. Peripheral Pin Select is performed in software and generally does not require the device to be reprogrammed. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping once it has been established.

10.4.1 AVAILABLE PINS

The Peripheral Pin Select feature is used with a range of up to 25 pins, depending on the particular device and its pin count. Pins that support the Peripheral Pin Select feature include the designation "RPn" in their full pin designation, where "n" is the remappable pin number.

See Table 1-2 for a summary of pinout options in each package offering.

10.4.2 AVAILABLE PERIPHERALS

The peripherals managed by the Peripheral Pin Select are all digital only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer related peripherals (input capture and output compare) and external interrupt inputs. Also included are the outputs of the comparator module, since these are discrete digital signals.

Peripheral Pin Select is not available for I^2C™ change notification inputs, RTCC alarm outputs or peripherals with analog inputs.

A key difference between pin select and non pin select peripherals is that pin select peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, non pin select peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

10.4.2.1 Peripheral Pin Select Function Priority

Pin-selectable peripheral outputs (for example, OC and UART transmit) take priority over any general purpose digital functions permanently tied to that pin, such as PMP and port I/O. Specialized digital outputs, such as USB functionality, take priority over PPS outputs on the same pin. The pin diagrams at the beginning of this data sheet list peripheral outputs in order of priority. Refer to them for priority concerns on a particular pin.

Unlike devices with fixed peripherals, pin-selectable peripheral inputs never take ownership of a pin. The pin's output buffer is controlled by the pin's TRIS bit setting, or by a fixed peripheral on the pin. If the pin is configured in Digital mode, then the PPS input will operate correctly, reading the input. If an analog function is enabled on the same pin, the pin-selectable input will be disabled.

EQUATION 15-1: RELATIONSHIP BETWEEN DEVICE AND SPI CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2, Doze mode and PLL are disabled.

TABLE 15-1: SAMPLE SCK FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2, Doze mode and PLL are disabled.

2: SCKx frequencies are shown in kHz.

REGISTER 18-2: PMMODE: PARALLEL PORT MODE REGISTER

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUSY	IRQM1	IRQM0	INCM1	INCM0	MODE16	MODE1	MODE0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAITB1(1)	WAITB0(1)	WAITM3	WAITM2	WAITM1	WAITM0	WAITE1(1)	WAITE0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **BUSY:** Busy bit (Master mode only)
1 = Port is busy (not useful when the processor stall is active)
0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits
11 = Interrupt generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode), or on a read or write operation when PMA<1:0> = 11 (Addressable PSP mode only)
10 = No interrupt is generated, processor stall activated
01 = Interrupt is generated at the end of the read/write cycle
00 = No interrupt is generated

bit 12-11 **INCM<1:0>:** Increment Mode bits
11 = PSP read and write buffers auto-increment (Legacy PSP mode only)
10 = Decrement ADDR<10:0> by 1 every read/write cycle
01 = Increment ADDR<10:0> by 1 every read/write cycle
00 = No increment or decrement of address

bit 10 **MODE16:** 8/16-Bit Mode bit
1 = 16-bit mode: Data register is 16 bits; a read or write to the Data register invokes two 8-bit transfers
0 = 8-bit mode: Data register is 8 bits; a read or write to the Data register invokes one 8-bit transfer

bit 9-8 **MODE<1:0>:** Parallel Port Mode Select bits
11 = Master Mode 1 (PMCS1, PMRD/$\overline{\text{PMWR}}$, PMENB, PMBE, PMA<x:0> and PMD<7:0>)
10 = Master Mode 2 (PMCS1, PMRD, $\overline{\text{PMWR}}$, $\overline{\text{PMBE}}$, PMA<x:0> and PMD<7:0>)
01 = Enhanced PSP control signals ($\overline{\text{PMRD}}$, $\overline{\text{PMWR}}$, $\overline{\text{PMCS1}}$, PMD<7:0> and PMA<1:0>)
00 = Legacy Parallel Slave Port control signals ($\overline{\text{PMRD}}$, $\overline{\text{PMWR}}$, $\overline{\text{PMCS1}}$ and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write Wait State Configuration bits(1)
11 = Data wait of 4 TCY; multiplexed address phase of 4 TCY
10 = Data wait of 3 TCY; multiplexed address phase of 3 TCY
01 = Data wait of 2 TCY; multiplexed address phase of 2 TCY
00 = Data wait of 1 TCY; multiplexed address phase of 1 TCY

bit 5-2 **WAITM<3:0>:** Read to Byte Enable Strobe Wait State Configuration bits
1111 = Wait of additional 15 TCY
...
0001 = Wait of additional 1 TCY
0000 = No additional wait cycles (operation forced into one TCY)

bit 1-0 **WAITE<1:0>:** Data Hold After Strobe Wait State Configuration bits(1)
11 = Wait of 4 TCY
10 = Wait of 3 TCY
01 = Wait of 2 TCY
00 = Wait of 1 TCY

Note 1: WAITB and WAITE bits are ignored whenever WAITM<3:0> = 0000.

FIGURE 18-5: MASTER MODE, PARTIALLY MULTIPLEXED ADDRESSING (SEPARATE READ AND WRITE STROBES, SINGLE CHIP SELECT)

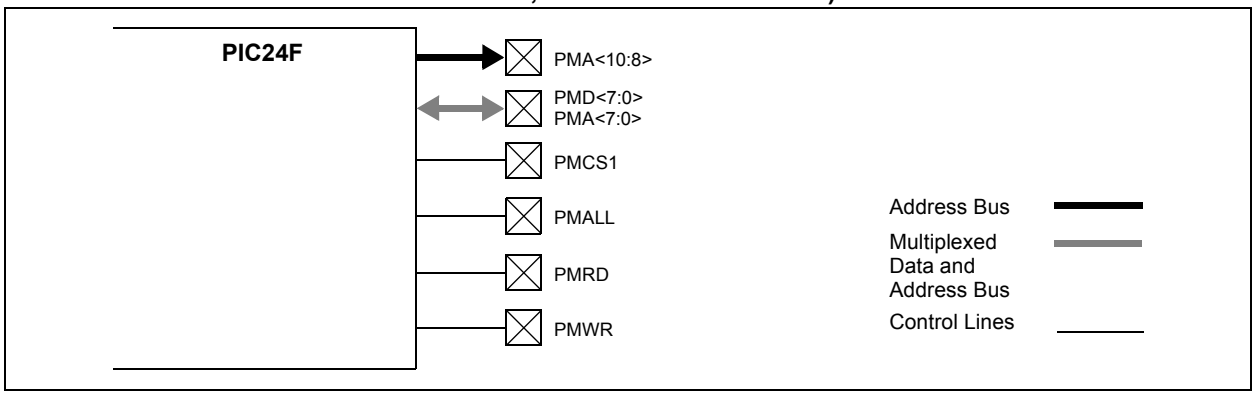


FIGURE 18-6: MASTER MODE, FULLY MULTIPLEXED ADDRESSING (SEPARATE READ AND WRITE STROBES, SINGLE CHIP SELECT)

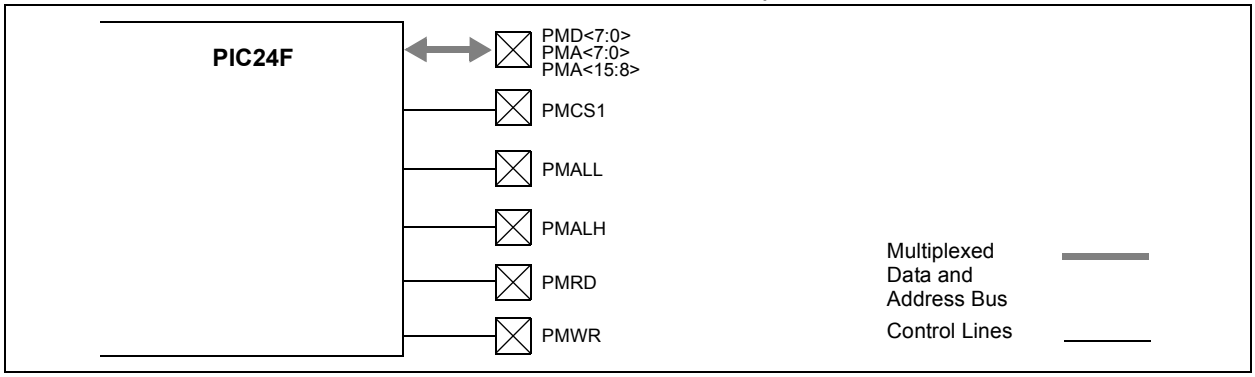


FIGURE 18-7: EXAMPLE OF A MULTIPLEXED ADDRESSING APPLICATION

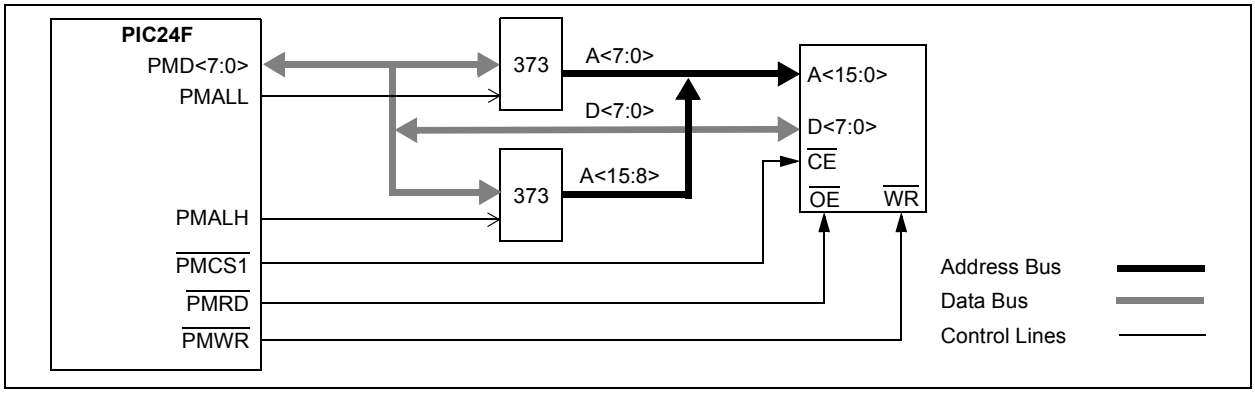
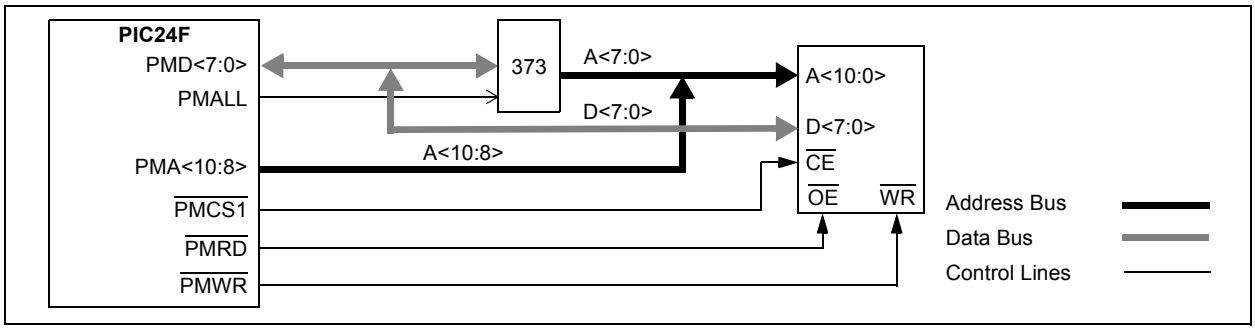


FIGURE 18-8: EXAMPLE OF A PARTIALLY MULTIPLEXED ADDRESSING APPLICATION



20.1 User Interface

20.1.1 POLYNOMIAL INTERFACE

The CRC module can be programmed for CRC polynomials of up to the 32nd order, using up to 32 bits. Polynomial length, which reflects the highest exponent in the equation, is selected by the PLEN<4:0> bits (CRCCON2<4:0>).

The CRCXORL and CRCXORH registers control which exponent terms are included in the equation. Setting a particular bit includes that exponent term in the equation; functionally, this includes an XOR operation on the corresponding bit in the CRC engine. Clearing the bit disables the XOR.

For example, consider two CRC polynomials, one a 16-bit equation and the other, a 32-bit equation:

$$x16 + x12 + x5 + 1$$

and

$$x32 + x26 + x23 + x22 + x16 + x12 + x11 + x10 + x8 + x7 + x5 + x4 + x2 + x + 1$$

To program these polynomials into the CRC generator, set the register bits as shown in Table 20-1.

Note that the appropriate positions are set to '1' to indicate that they are used in the equation (for example, X26 and X23). The 0 bit required by the equation is always XORed; thus, X0 is a don't care. For a polynomial of length N, it is assumed that the *N*th bit will always be used, regardless of the bit setting. Therefore, for a polynomial length of 32, there is no 32nd bit in the CRCxOR register.

20.1.2 DATA INTERFACE

The module incorporates a FIFO that works with a variable data width. Input data width can be configured to any value between one and 32 bits using the DWIDTH<4:0> bits (CRCCON2<12:8>). When the data width is greater than 15, the FIFO is four words deep. When the DWIDTH value is between 15 and 8, the FIFO is 8 words deep. When the DWIDTH value is less than 8, the FIFO is 16 words deep.

The data for which the CRC is to be calculated must first be written into the FIFO. Even if the data width is less than 8, the smallest data element that can be written into the FIFO is one byte. For example, if the DWIDTH value is five, then the size of the data is DWIDTH + 1, or six. The data is written as a whole byte; the two unused upper bits are ignored by the module.

Once data is written into the MSb of the CRCDAT registers (that is, MSb as defined by the data width), the value of the VWORD<4:0> bits (CRCCON1<12:8>) increments by one. For example, if the DWIDTH value is 24, the VWORD bits will increment when bit 7 of CRCDATH is written. Therefore, CRCDATL must always be written before CRCDATH.

The CRC engine starts shifting data when the CRCGO bit is set and the value of VWORD is greater than zero. Each word is copied out of the FIFO into a buffer register, which decrements VWORD. The data is then shifted out of the buffer. The CRC engine continues shifting at a rate of two bits per instruction cycle, until the VWORD value reaches zero. This means that for a given data width, it takes half that number of instructions for each word to complete the calculation. For example, it takes 16 cycles to calculate the CRC for a single word of 32-bit data.

When the VWORD value reaches the maximum value for the configured value of DWIDTH (4, 8 or 16), the CRCFUL bit becomes set. When the VWORD value reaches zero, the CRCMPT bit becomes set. The FIFO is emptied and the VWORD<4:0> bits are set to '00000' whenever CRCEN is '0'.

At least one instruction cycle must pass, after a write to CRCDAT, before a read of the VWORD bits is done.

TABLE 20-1: CRC SETUP EXAMPLES FOR 16 AND 32-BIT POLYNOMIAL

CRC Control Bits	Bit Values	
	16-Bit Polynomial	32-Bit Polynomial
PLEN<4:0>	01111	11111
X<31:16>	0000 0000 0000 000x	0000 0100 1100 0001
X<15:0>	0001 0000 0010 000x	0001 1101 1011 011x

21.0 10-BIT HIGH-SPEED A/D CONVERTER

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **Section 17. "10-Bit A/D Converter"** (DS39705).

The 10-bit A/D Converter has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 500 ksps
- 13 analog input pins
- External voltage reference input pins
- Internal band gap reference inputs
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable Buffer Fill modes
- Four result alignment options
- Operation during CPU Sleep and Idle modes

On all PIC24FJ64GA104 family devices, the 10-bit A/D Converter has 13 analog input pins, designated AN0 through AN12. In addition, there are two analog input pins for external voltage reference connections (V_{REF}+ and V_{REF}-). These voltage reference inputs may be shared with other analog input pins.

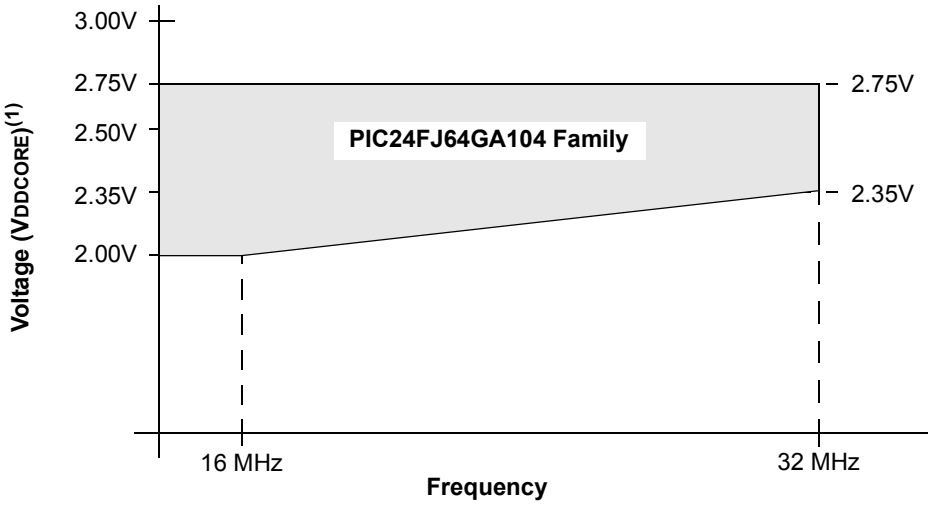
A block diagram of the A/D Converter is shown in Figure 21-1.

To perform an A/D conversion:

1. Configure the A/D module:
   a) Configure port pins as analog inputs and/or select band gap reference inputs (AD1PCFGL<15:0> and AD1PCFGH<1:0>).
   b) Select voltage reference source to match expected range on analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:5> and AD1CON3<12:8>).
   e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select interrupt rate (AD1CON2<5:2>).
   g) Turn on A/D module (AD1CON1<15>).
2. Configure the A/D interrupt (if required):
   a) Clear the AD1IF bit.
   b) Select A/D interrupt priority.

28.1 DC Characteristics

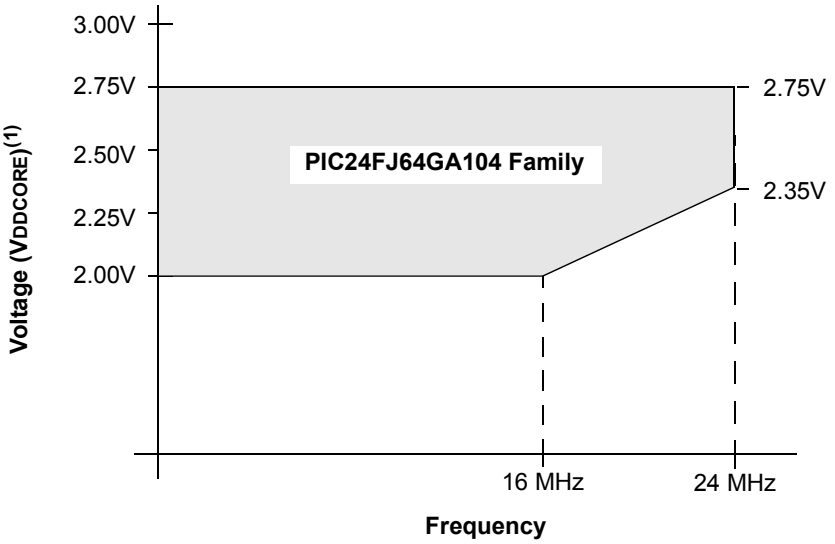
FIGURE 28-1: PIC24FJ64GA104 FAMILY VOLTAGE/FREQUENCY GRAPH (INDUSTRIAL)



For frequencies between 16 MHz and 32 MHz, FMAX = (45.7 MHz/V) * (VDDCORE – 2V) + 16 MHz.

Note 1: When the voltage regulator is disabled, VDD and VDDCORE must be maintained so that VDDCORE ≤ VDD ≤ 3.6V.

FIGURE 28-2: PIC24FJ64GA104 FAMILY VOLTAGE/FREQUENCY GRAPH (EXTENDED TEMPERATURE)



For frequencies between 16 MHz and 24 MHz, FMAX = (22.9 MHz/V) * (VDDCORE – 2V) + 16 MHz.

Note 1: When the voltage regulator is disabled, VDD and VDDCORE must be maintained so that VDDCORE ≤ VDD ≤ 3.6V.

TABLE 28-9: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
DO10		I/O Ports	—	—	0.4	V	IOL = 8.5 mA, VDD = 3.6V
			—	—	0.4	V	IOL = 5.0 mA, VDD = 2.0V
DO16		I/O Ports	—	—	0.4	V	IOL = 8.0 mA, VDD = 3.6V, 125°C
			—	—	0.4	V	IOL = 4.5 mA, VDD = 2.0V, 125°C
	VOH	**Output High Voltage**					
DO20		I/O Ports	3.0	—	—	V	IOH = -3.0 mA, VDD = 3.6V
			2.4	—	—	V	IOH = -6.0 mA, VDD = 3.6V
			1.65	—	—	V	IOH = -1.0 mA, VDD = 2.0V
			1.4	—	—	V	IOH = -3.0 mA, VDD = 2.0V
DO26		I/O Ports	3.0	—	—	V	IOH = -2.5 mA, VDD = 3.6V, 125°C
			1.65	—	—	V	IOH = -0.5 mA, VDD = 2.0V, 125°C

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 28-10: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
	VPEW	Supply Voltage for Self-Timed Writes					
D132A		VDDCORE	2.25	—	3.6	V	
D132B		VDD	2.35	—	3.6	V	
D133A	TIW	Self-Timed Write Cycle Time	—	3	—	ms	
D133B	TIE	Self-Timed Page Erase Time	40	—	—	ms	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	7	—	mA	

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

FIGURE 28-4: EXTERNAL CLOCK TIMING

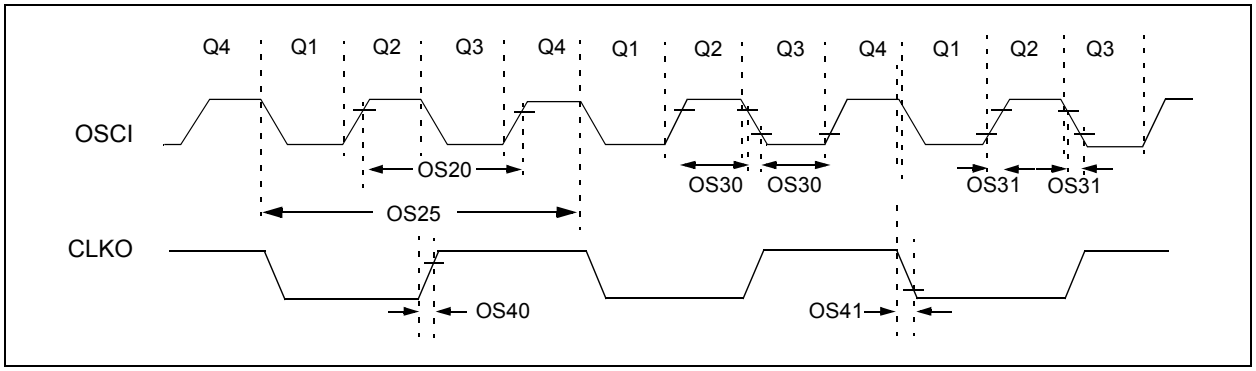


TABLE 28-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.50 to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC mode)	DC 4 DC 4	— — — —	32 8 24 6	MHz MHz MHz MHz	EC, -40°C ≤ TA ≤ +85°C ECPLL, -40°C ≤ TA ≤ +85°C EC, -40°C ≤ TA ≤ +125°C ECPLL, -40°C ≤ TA ≤ +125°C
		Oscillator Frequency	3 3 10 31 3 10	— — — — — —	10 8 32 33 6 24	MHz MHz MHz kHz MHz MHz	XT XTPLL, -40°C ≤ TA ≤ +85°C HS, -40°C ≤ TA ≤ +85°C SOSC XTPLL, -40°C ≤ TA ≤ +125°C HS, -40°C ≤ TA ≤ +125°C
OS20	TOSC	TOSC = 1/FOSC	—	—	—	—	See parameter OS10 for FOSC value
OS25	TCY	Instruction Cycle Time(2)	62.5	—	DC	ns	
OS30	TosL, TosH	External Clock in (OSCI) High or Low Time	0.45 x TOSC	—	—	ns	EC
OS31	TosR, TosF	External Clock in (OSCI) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3)	—	6	10	ns	
OS41	TckF	CLKO Fall Time(3)	—	6	10	ns	

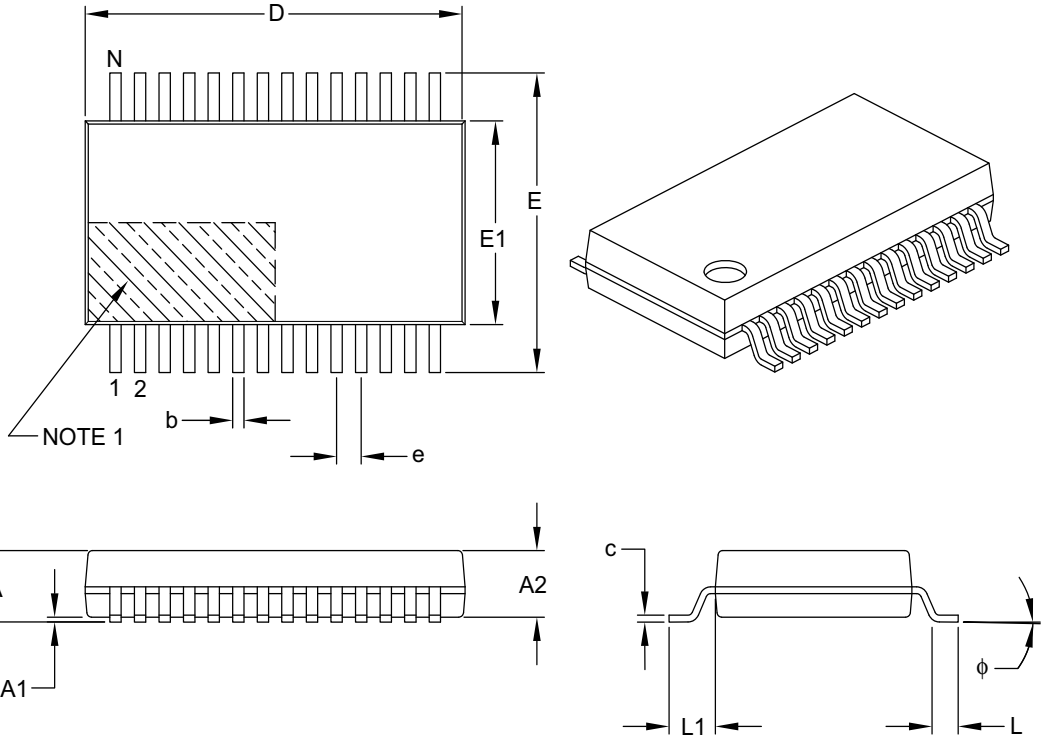
Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Instruction cycle period (TCY) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSCI/CLKI pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSCO pin. CLKO is low for the Q1-Q2 period (1/2 TCY) and high for the Q3-Q4 period (1/2 TCY).

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

APPENDIX A: REVISION HISTORY

Revision A (August 2009)

Original data sheet for the PIC24FJ64GA104 family of devices.

Revision B (October 2009)

Corrected **Section 10.3 "Input Change Notification"** regarding the number of ICN inputs and the availability of pull-downs.

Updated **Section 10.4.2 "Available Peripherals"** by removing the Timer 1 clock input from Table 10-2.

Updated **Section 28.1 "DC Characteristics"** as follows:

- Added new specifications to Tables 29-4 and 29-5 for IDD and IIDLE at 0.5 MIPS operation.
- Updated Table 29-4 with revised maximum IDD specifications for 1 MIP and 4 MIPS.
- Renumbered the parameters for the delta IPD current (32 kHz, SOSCEL = 11) from DC62*n* to DC63*n*.

Revision C (August 2010)

This revision includes the following updates:

Pin Diagrams

- Updated Pin 7 and Pin 14 in 28-Pin SPDIP, SOIC.
- Updated the device name, Pin13 and Pin 23, in 28-Pin QFN.

Removed IEC5, IFS5 and IPC21 rows from Table 4-5.

Updated CLKDIV bit details in Table 4-23.

Removed JTAG from Flash programming list in **Section 5.0 "Flash Program Memory"**.

Updated **Section 10.4.5 "Considerations for Peripheral Pin Selection"** as follows:

- Replaced the code in Example 10-2.
- Added the new code as Example 10-3.

Updated shaded note in **Section 20.0 "32-Bit Programmable Cyclic Redundancy Check (CRC) Generator"** and **Section 22.0 "Triple Comparator Module"**.

Updated **Section 28.1 "DC Characteristics"** as follows:

- Updated the device name in Table 28-1.
- Added the "125°C data" in Table 28-4,Table 28-5,Table 28-6 and Table 28-7.
- Updated Min and Typ columns of DC16 in Table 28-3.
- Added rows, AD08 and AD09, in Table 28-22.
- Added Figure 28-2.

Added the 28-pin SSOP package to **Section 29.0 "Packaging Information"**.

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